ABSTRACT

The present invention relates to a method of temporarily and firmly fixing two solids to each other and to a composition used in the method, which is a method of temporarily fixing, comprising temporarily fixing the two solids to each other with a liquid crystal compound or a composition comprising the liquid crystal compound. This method is used for a method of temporarily fixing a pad for chemical mechanical polishing, for example, to polish a wafer for a semiconductor device fixed on a surface of a base plate, when one solid is a pad for chemical mechanical polishing of a wafer for a semiconductor device and the other is a base plate to fix the pad.



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